Solderite Flux WPF21

Introduction：

Various protective methods are used for the protection of copper foil of printed circuit boards. It is predicted, however, that the use of lead contained in the organic solvent of resin-based pre-flux and in solder leveler will be strictly controlled in future from the need of dealing with environmental problems. Under such circumstances, large expectation is placed on water-soluble heat-resistant pre-flux.

However, the use of water-soluble pre-flux has been limited because of the problem of solderability and the problem of discoloring gold-plated section when the pre-flux was used for circuit boards having gold-plated sections. Water-soluble heat-resistant pre-flux having excellent solderability, WPF-21, was now developed to cope with the problem of discoloration of gold-plated sections. It will prevent the discoloration of gold-plated sections.

Outstanding Features：

- Discoloration of gold-plated section will be prevented.
- Organic film coat excellent in heat and humidity resistance is formed on the surface of copper.
- Heal resistance is improved as compared with the conventional water-soluble pre-flux.
- Excellent solderability is shown even after reflow processing of plural number of times.
- Excellent in the spread of wettability of solder paste.
- Excellent in the flow solderability of lead-free solder.
- Film coat will be formed in a processing time from 60 to 90 seconds.
- Thin and uniform film is formed to produce excellent in copper foil land, so that the material is suited for high density packaging boards.
- No flammability as no organic solvent is contained.

Specifications：

Appearance	：Slightly whitish transparent liquid
Specific gravity	：1.03±0.01 （20℃）
PH	：3.30±0.05 （20℃）
Acid value	：125±10
Concentration of effective ingredient	：100±10％